

Demonstration and Characterization of High-Resolution 4H-SiC Schottky Diode Alpha Particle Detectors at High Temperature

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The Ohio State University

ETI Annual Workshop

February 20 – 21, 2024, Golden, CO









Objective: Demonstrate and characterize Schottky diode radiation detectors fabricated on 4H-SiC at high temperatures.

Completed Tasks:

- Fabricated Schottky diodes on 4H-SiC
- Measured electronic performance up to 500 °C
- Determined detector characteristics up to 500 °C
- Demonstrated high-resolution alpha particle spectroscopy at room temperature
- Measured room temperature detector characteristics and spectroscopy capabilities prior to heating up to 400 °C



Fabricated 4H-SiC Schottky Diodes



Silicon Carbide Epitaxial Layer:

- **Π** Thickness: 20 μm
- **D** Doping Concentration: 2.4×10^{14} cm⁻³
- Dopant: Nitrogen

Contacts:

- □ Schottky Contact: 50 nm Nickel
- Contact Area: 2 mm²
- □ Ohmic Contact 50 nm Titanium/Gold Stack

Device Characteristics:

- □ Theoretical Schottky barrier height: 1.91 eV
- □ Theoretical Full Depletion Voltage: 75 V

Ti/Au

Ni (50 nm)

Epitaxial SiC (20 µm)

SiC Substrate







Spectroscopy Capabilities:



We have fabricated high resolution 4H-SiC Schottky diode radiation detectors:

□ Am-241 – 5.486 MeV peak FWHM: 21 keV (0.38%)





High Temperature Electronic Characterization





- Signatone High Temperature hot chuck in dark box electronic probe station
 Heating capability up to 500 °C
- 4H-SiC Schottky diodes are electronically characterized up to 500
 °C at 100 °C increments
- Electronic characterization includes:
 Current-Voltage sweeps
 Capacitance-Voltage sweeps
 Current vs Time at 60 V reverse bias



High Temperature Electronic Characterization

- Leakage current should remain below 1 μA to obtain spectroscopy
- Leakage current should remain below 1 nA to obtain high-resolution spectroscopy







High Temperature Electronic Characterization



The built in voltage can be extracted from the inverse capacitance squared by extrapolation
 As the temperature increases the Fermi level of the SiC increases resulting in a lowering of the barrier height







Post-Heating:



Ti/Au Ohmic Contact:

Ni Schottky Contact:





Electronic Characteristics Post-Heating



- Severe degradation of the nickel Schottky contact has occurred prior to heating at 500 °C
- Room temperature leakage current at 60 V reverse bias remains around 10 pA up to 300 °C heating and increases to 1 nA following 400 °C heating
- Built-in voltage at room temperature remains constant prior to heating up to 400 °C





Post-Heating Spectroscopy





Despite the increase in leakage current at 60 V after 400 °C heating, minimal loss in resolution has occurred



Post-Heating Spectroscopy Data



FWHM increase from 50 channels before heating to 58 channels post 400 °C heating □ Resolution increases from 0.385% to 0.446% post 400 °C heating Shift in Peak Channel Number 13020 Channel No. 13000 12980 12960 200 0 100 300 400 Temperature (°C)

Centroid peak channel remains within 10 channels





Devices as fabricated show electronic stability up to 300 °C

- Room temperature spectroscopy remains relatively unchanged post heating up to 400 °C
- Contact degradation at 500 °C needs to be investigated
- Leakage current at elevated temperatures need to be reduced
 Passivation layers, guard rings, etc.
- □A more robust Schottky contact will be necessary for operation at temperatures exceeding 500 °C



High Temperature Spectroscopy Station Design Criteria:

- □ High temperature 1" sample heater Max Temp.: 800 – 1000 °C
- Isolated sample platform to minimize electronic noise
- □ Variable source mounting fixture
- Vacuum chamber environment
- Low noise high-voltage feed though to power and interface with detector





ACKNOWLEDGEMENTS

This material is based upon work supported by the Department of Energy / National Nuclear Security Administration under Award Number(s) DE-NA0003921.

